Renesas Electronics America Inc - R5F2L3A7CDFA#U1 Datasheet

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	LCD, POR, PWM, Voltage Detect, WDT
Number of I/O	88
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 20x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-QFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2l3a7cdfa-u1

1.1.2 Differences between Groups

Table 1.1 lists the Differences between Groups, Table 1.2 lists the Programmable I/O Ports Provided for Each Group, and Table 1.3 lists the LCD Display Function Pins Provided for Each Group. Figures 1.9 to 1.13 show the Pin Assignment for Each Group, and Tables 1.7 to 1.10 list Product Information.
The explanations in the chapters which follow apply to the R8C/L3AC Group only. Note the differences shown below.

Table 1.1 Differences between Groups

Item	Function	R8C/L35C Group	R8C/L36C Group	R8C/L38C Group	R8C/L3AC Group
I/O Ports	Programmable I/O ports	41 pins	52 pins	68 pins	88 pins
	High current drive ports	5 pins	8 pins	8 pins	16 pins
Interrupts	$\overline{\text{INT}}$ interrupt pins	5 pins	8 pins	8 pins	8 pins
	Key input interrupt pins	4 pins	4 pins	8 pins	8 pins
Timer RA	Timer RA output pin	None	1 pin	1 pin	1 pin
Timer RB	Timer RB output pin	None	1 pin	1 pin	1 pin
Timer RD	Timer RD I/O pin	None	None	8 pins	8 pins
Timer RE	Timer RE output pin	None	1 pin	1 pin	1 pin
Timer RG	Timer RG I/O pin	None	None	None	2 pins
	Timer RG output pin	None	None	None	2 pins
A/D Converter	Analog input pin	10 pins	10 pins	16 pins	20 pins
LCD Drive Control Circuit	LCD power supply	3 pins (VL1, VL2, VL4)	4 pins (VL1 to VL4)	4 pins (VL1 to VL4)	4 pins (VL1 to VL4)
	Common output pins	Max. 4 pins	Max. 8 pins	Max. 8 pins	Max. 8 pins
	Segment output pins	Max. 24 pins	Max. 32 pins	Max. 48 pins	Max. 56 pins
Packages		52-pin LQFP	64-pin LQFP	80-pin LQFP	100-pin LQFP/ 100-pin QFP

Note:
1. I/O ports are shared with I/O functions, such as interrupts or timers.
Refer to **Tables 1.11 to 1.13, Pin Name Information by Pin Number**, for details.

1.1.3 Specifications

Tables 1.4 to 1.6 list the Specifications.

Table 1.4 Specifications (1)

Item	Function		Specification
CPU	Central processing unit		R8C CPU core • Number of fundamental instructions: 89 • Minimum instruction execution time: 50 ns (f(XIN) = 20 MHz, VCC = 2.7 to 5.5 V) 200 ns (f(XIN) = 5 MHz, VCC = 1.8 to 5.5 V) • Multiplier: 16 bits × 16 bits → 32 bits • Multiply-accumulate instruction: 16 bits × 16 bits + 32 bits → 32 bits • Operating mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM/RAM Data flash		Refer to **Tables 1.7 to 1.10 Product Lists**.
Power Supply Voltage Detection	Voltage detection circuit		• Power-on reset • Voltage detection 3 (detection level of voltage detection 0 and voltage detection 1 selectable)
I/O Ports	Programmable I/O ports	R8C/L35C Group	• CMOS I/O ports: 41, selectable pull-up resistor • High current drive ports: 5
		R8C/L36C Group	• CMOS I/O ports: 52, selectable pull-up resistor • High current drive ports: 8
		R8C/L38C Group	• CMOS I/O ports: 68, selectable pull-up resistor • High current drive ports: 8
		R8C/L3AC Group	• CMOS I/O ports: 88, selectable pull-up resistor • High current drive ports: 16
Clock	Clock generation circuits		4 circuits: XIN clock oscillation circuit XCIN clock oscillation circuit (32 kHz) High-speed on-chip oscillator (with frequency adjustment function) Low-speed on-chip oscillator • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Division ratio selectable from 1, 2, 4, 8, and 16 • Low-power-consumption modes: Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode, power-off mode
			Real-time clock (timer RE)
Interrupts		R8C/L35C Group	• Number of interrupt vectors: 69 • External Interrupt: 9 ($\overline{\text{INT}}$ × 5, key input × 4) • Priority levels: 7 levels
		R8C/L36C Group	• Number of interrupt vectors: 69 • External Interrupt: 12 ($\overline{\text{INT}}$ × 8, key input × 4) • Priority levels: 7 levels
		R8C/L38C Group	• Number of interrupt vectors: 69 • External Interrupt: 16 ($\overline{\text{INT}}$ × 8, key input × 8) • Priority levels: 7 levels
		R8C/L3AC Group	• Number of interrupt vectors: 69 • External Interrupt: 16 ($\overline{\text{INT}}$ × 8, key input × 8) • Priority levels: 7 levels
Watchdog Timer			• 14 bits × 1 (with prescaler) • Selectable reset start function • Selectable low-speed on-chip oscillator for watchdog timer
DTC (Data Transfer Controller)			• 1 channel • Activation sources: 38 • Transfer modes: 2 (normal mode, repeat mode)

Table 1.9 Product List for R8C/L38C Group **Current of Apr 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2L387CNFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0080KB-A	N Version
R5F2L387CNFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0080JA-A	
R5F2L388CNFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0080KB-A	
R5F2L388CNFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0080JA-A	
R5F2L38ACNFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080KB-A	
R5F2L38ACNFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080JA-A	
R5F2L38CCNFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080KB-A	
R5F2L38CCNFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080JA-A	
R5F2L387CDFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0080KB-A	D Version
R5F2L387CDFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0080JA-A	
R5F2L388CDFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0080KB-A	
R5F2L388CDFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0080JA-A	
R5F2L38ACDFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080KB-A	
R5F2L38ACDFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080JA-A	
R5F2L38CCDFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080KB-A	
R5F2L38CCDFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080JA-A	

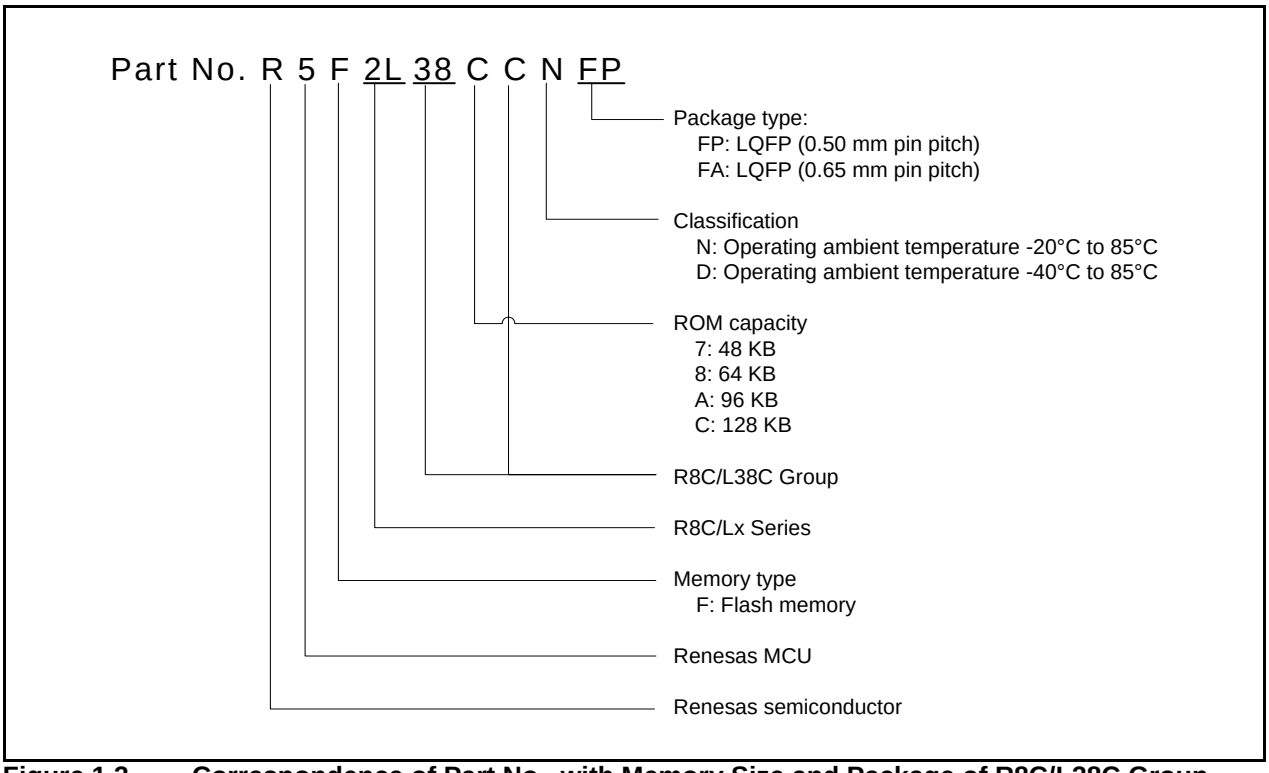


Figure 1.3 Correspondence of Part No., with Memory Size and Package of R8C/L38C Group

Table 1.10 Product List for R8C/L3AC Group **Current of Apr 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2L3A7CNFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0100KB-A	N Version
R5F2L3A7CNFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PRQP0100JD-B	
R5F2L3A8CNFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0100KB-A	
R5F2L3A8CNFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PRQP0100JD-B	
R5F2L3AACNFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0100KB-A	
R5F2L3AACNFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PRQP0100JD-B	
R5F2L3ACCNFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0100KB-A	
R5F2L3ACCNFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PRQP0100JD-B	
R5F2L3A7CDFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0100KB-A	D Version
R5F2L3A7CDFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PRQP0100JD-B	
R5F2L3A8CDFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0100KB-A	
R5F2L3A8CDFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PRQP0100JD-B	
R5F2L3AACDFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0100KB-A	
R5F2L3AACDFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PRQP0100JD-B	
R5F2L3ACCDFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0100KB-A	
R5F2L3ACCDFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PRQP0100JD-B	

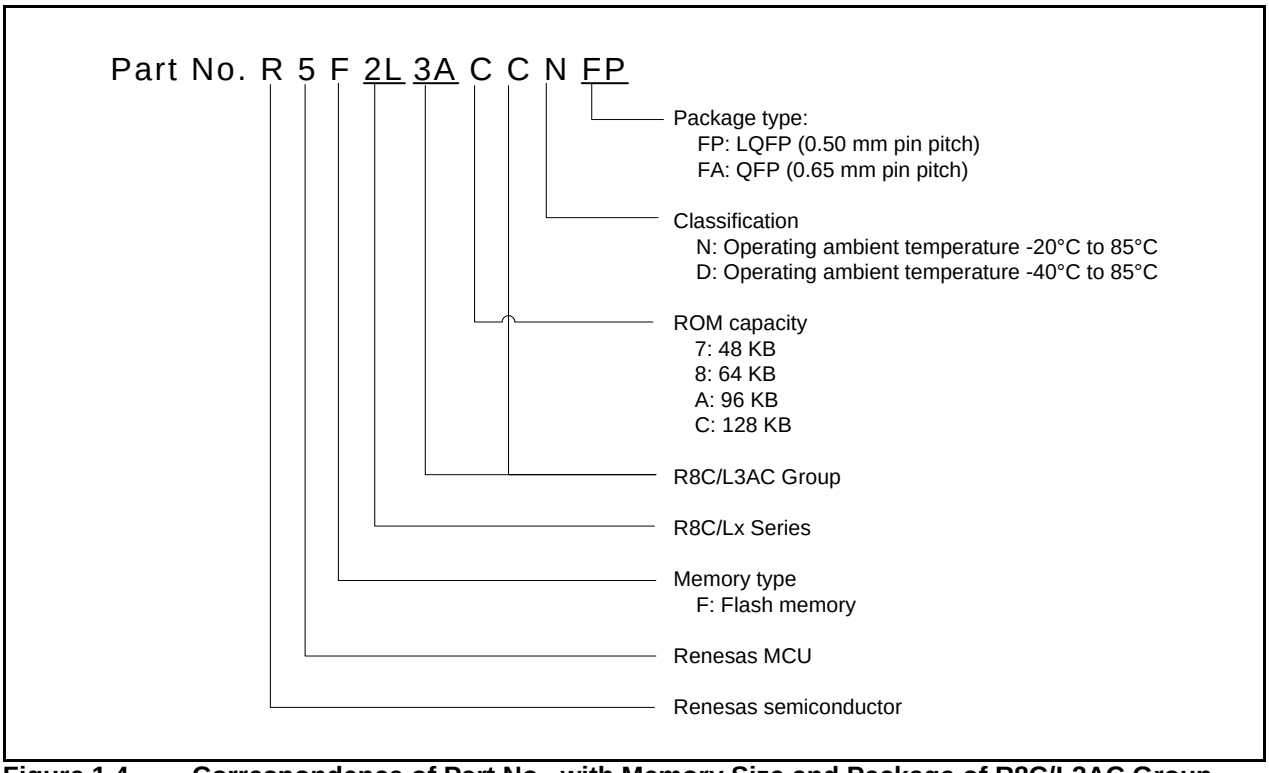


Figure 1.4 Correspondence of Part No., with Memory Size and Package of R8C/L3AC Group

1.3 Block Diagrams

Figure 1.5 shows a Block Diagram of R8C/L35C Group. Figure 1.6 shows a Block Diagram of R8C/L36C Group. Figure 1.7 shows a Block Diagram of R8C/L38C Group. Figure 1.8 shows a Block Diagram of R8C/L3AC Group.

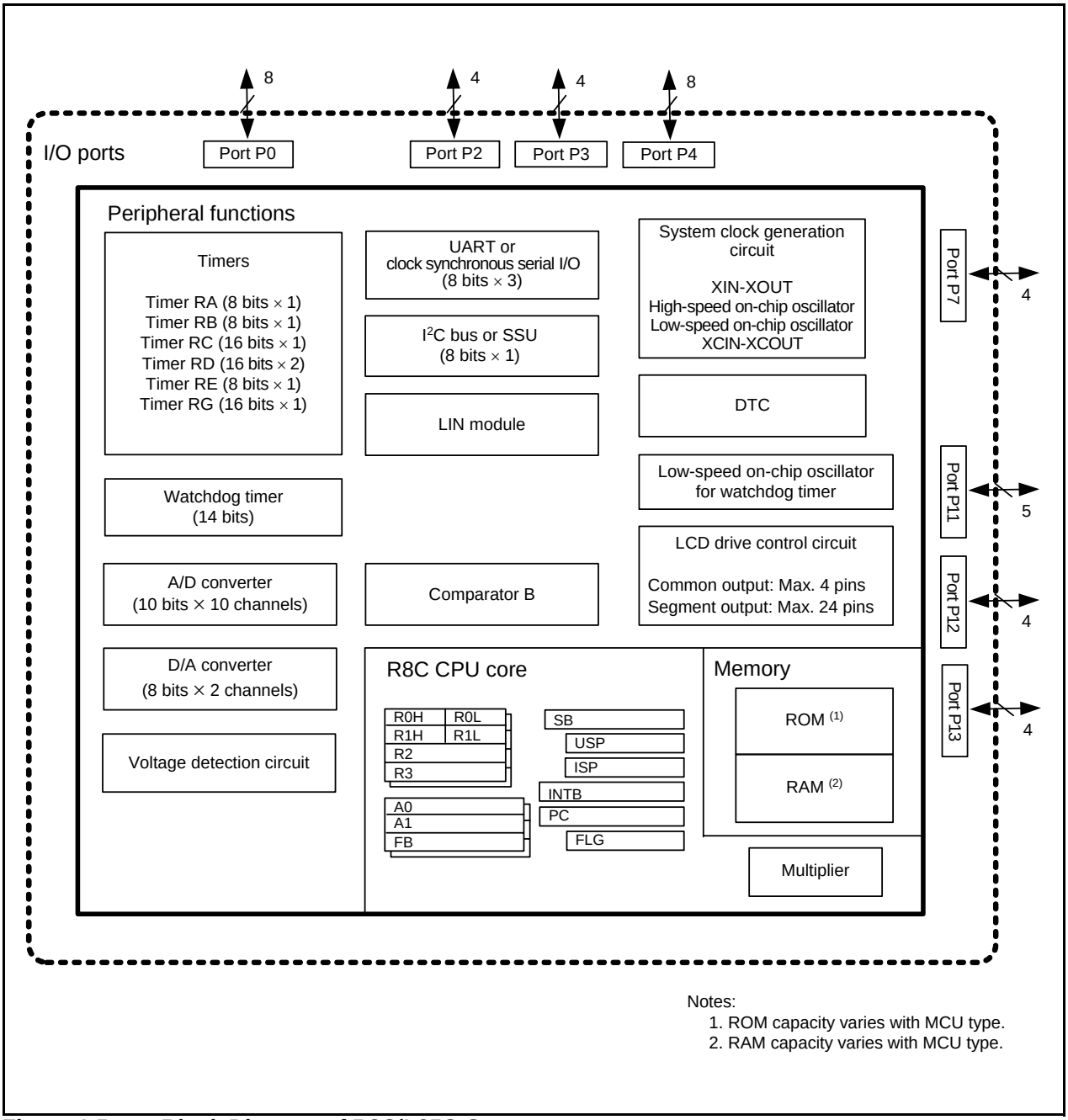
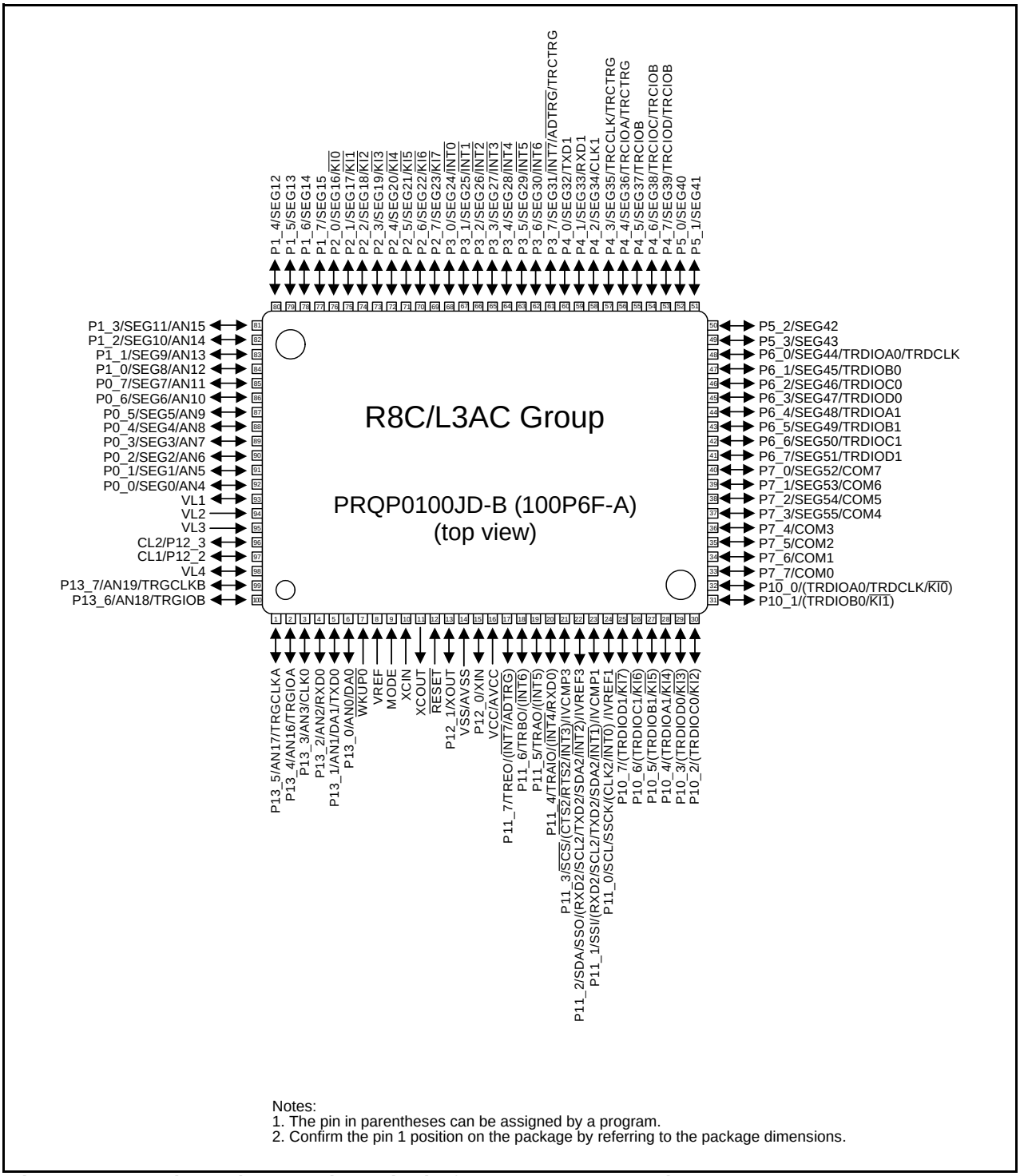


Figure 1.5 Block Diagram of R8C/L35C Group



Notes:
1. The pin in parentheses can be assigned by a program.
2. Confirm the pin 1 position on the package by referring to the package dimensions.

Figure 1.13 Pin Assignment (Top View) of PRQP0100JD-B Package

Table 1.12 Pin Name Information by Pin Number (2)

Pin Number				Control Pin	Port	I/O Pin Functions for Peripheral Modules						
L3AC (Note 2)	L38C	L36C	L35C			Interrupt	Timer	Serial Interface	SSU	I²C bus	A/D Converter, D/A Converter, Comparator B	LCD drive control circuit
40 [42]	31				P6_6		TRDIOC1					SEG50
41 [43]	32				P6_5		TRDIOB1					SEG49
42 [44]	33				P6_4		TRDIOA1					SEG48
43 [45]	34				P6_3		TRDIOD0					SEG47
44 [46]	35				P6_2		TRDIOC0					SEG46
45 [47]	36				P6_1		TRDIOB0					SEG45
46 [48]	37				P6_0		TRDIOA0/ TRDCLK					SEG44
47 [49]					P5_3							SEG43
48 [50]					P5_2							SEG42
49 [51]					P5_1							SEG41
50 [52]					P5_0							SEG40
51 [53]	38	27	22		P4_7		TRCIOD/ TRCIOB					SEG39
52 [54]	39	28	23		P4_6		TRCIOC/ TRCIOB					SEG38
53 [55]	40	29	24		P4_5		TRCIOB					SEG37
54 [56]	41	30	25		P4_4		TRCIOA/ TRCTRG					SEG36
55 [57]	42	31	26		P4_3		TRCCLK/ TRCTRG					SEG35
56 [58]	43	32	27		P4_2			CLK1				SEG34
57 [59]	44	33	28		P4_1			RXD1				SEG33
58 [60]	45	34	29		P4_0			TXD1				SEG32
59 [61]	46	35			P3_7	$\overline{INT7}$	TRCTRG				$\overline{ADTRG}$	SEG31
60 [62]	47	36			P3_6	$\overline{INT6}$						SEG30
61 [63]	48	37			P3_5	$\overline{INT5}$						SEG29
62 [64]	49	38			P3_4	$\overline{INT4}$						SEG28
63 [65]	50	39	30		P3_3	$\overline{INT3}$						SEG27
64 [66]	51	40	31		P3_2	$\overline{INT2}$						SEG26
65 [67]	52	41	32		P3_1	$\overline{INT1}$						SEG25
66 [68]	53	42	33		P3_0	$\overline{INT0}$						SEG24
67 [69]	54	43	34		P2_7	$\overline{KI7}$						SEG23
68 [70]	55	44	35		P2_6	$\overline{KI6}$						SEG22
69 [71]	56	45	36		P2_5	$\overline{KI5}$						SEG21
70 [72]	57	46	37		P2_4	$\overline{KI4}$						SEG20
71 [73]	58				P2_3	$\overline{KI3}$						SEG19
72 [74]	59				P2_2	$\overline{KI2}$						SEG18
73 [75]	60				P2_1	$\overline{KI1}$						SEG17
74 [76]	61				P2_0	$\overline{KI0}$						SEG16
75 [77]					P1_7							SEG15
76 [78]					P1_6							SEG14
77 [79]					P1_5							SEG13
78 [80]					P1_4							SEG12
79 [81]	62				P1_3						AN15	SEG11
80 [82]	63				P1_2						AN14	SEG10
81 [83]	64				P1_1						AN13	SEG9
82 [84]	65				P1_0						AN12	SEG8
83 [85]	66	47	38		P0_7						AN11 (3)	SEG7
84 [86]	67	48	39		P0_6						AN10 (3)	SEG6

Notes:
1. The pin in parentheses can be assigned by a program.
2. The number in brackets indicates the pin number for the 100P6F package.
3. Pins AN10 and AN11 are not available in the R8C/L35C, and R8C/L36C Groups.

1.5 Pin Functions

Tables 1.14 and 1.15 list Pin Functions for R8C/L3AC Group.

Table 1.14 Pin Functions for R8C/L3AC Group (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	–	Apply 1.8 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	–	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Driving this pin low resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
Power-off mode exit input	$\overline{\text{WKUP0}}$	I	This pin is provided for input to exit the mode used in power-off mode. Connect to VSS when not using power-off mode.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic oscillator or a crystal oscillator between pins XIN and XOUT. (1) To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	O	
XCIN clock input	XCIN	I	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between pins XCIN and XCOUT. (1) To use an external clock, input it to the XCIN pin and leave the XCOUT pin open.
XCIN clock output	XCOUT	O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT7}}$	I	$\overline{\text{INT}}$ interrupt input pins.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI7}}$	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRAO	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Timer RC I/O pins
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O pins
	TRDCLK	I	External clock input pin
Timer RE	TREO	O	Divided clock output pin
Timer RG	TRGCLKA, TRGCLKB	I	Timer RG input pins
	TRGIOA, TRGIOB	I/O	Timer RG I/O pins
Serial interface	CLK0, CLK1, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD1, RXD2	I	Serial data input pins
	TXD0, TXD1, TXD2	O	Serial data output pins
	$\overline{\text{CTS2}}$	I	Transmission control input pin
	$\overline{\text{RTS2}}$	O	Reception control output pin
	SCL2	I/O	I^2C mode clock I/O pin
	SDA2	I/O	I^2C mode data I/O pin

I: Input O: Output I/O: Input and output

Note:

1. Contact the oscillator manufacturer for oscillation characteristics.

Table 1.15 Pin Functions for R8C/L3AC Group (2)

Item	Pin Name	I/O Type	Description
I^2C bus	SCL	I/O	Clock I/O pin
	SDA	I/O	Data I/O pin
SSU	SSI	I/O	Data I/O pin
	$\overline{SCS}$	I/O	Chip-select signal I/O pin
	SSCK	I/O	Clock I/O pin
	SSO	I/O	Data I/O pin
Reference voltage input	VREF	I	Reference voltage input pin for the A/D converter and the D/A converter
A/D converter	AN0 to AN11	I	A/D converter analog input pins
	$\overline{ADTRG}$	I	A/D external trigger input pin
D/A converter	DA0, DA1	O	D/A converter output pins
Comparator B	IVCMP1, IVCMP3	I	Comparator B analog voltage input pins
	IVREF1, IVREF3	I	Comparator B reference voltage input pins
I/O ports	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0, P5_3, P6_0 to P6_7 P7_0 to P7_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_3, P13_0 to P13_7	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. Ports P10_0 to P10_7 and P11_0 to P11_7 can be used as LED drive ports.
Segment output	SEG0 to SEG55	O	LCD segment output pins
Common output	COM0 to COM7	O	LCD common output pins
Voltage multiplier capacity connect pins	CL1, CL2	O	Connect pins for the LCD control voltage multiplier
LCD power supply	VL1	I/O	Apply the voltage: $0 \leq VL1 \leq VL2 \leq VL3 \leq VL4$. VL1 can be used as the reference potential input or output pin when setting the voltage multiplier.
	VL2 to VL4	I	

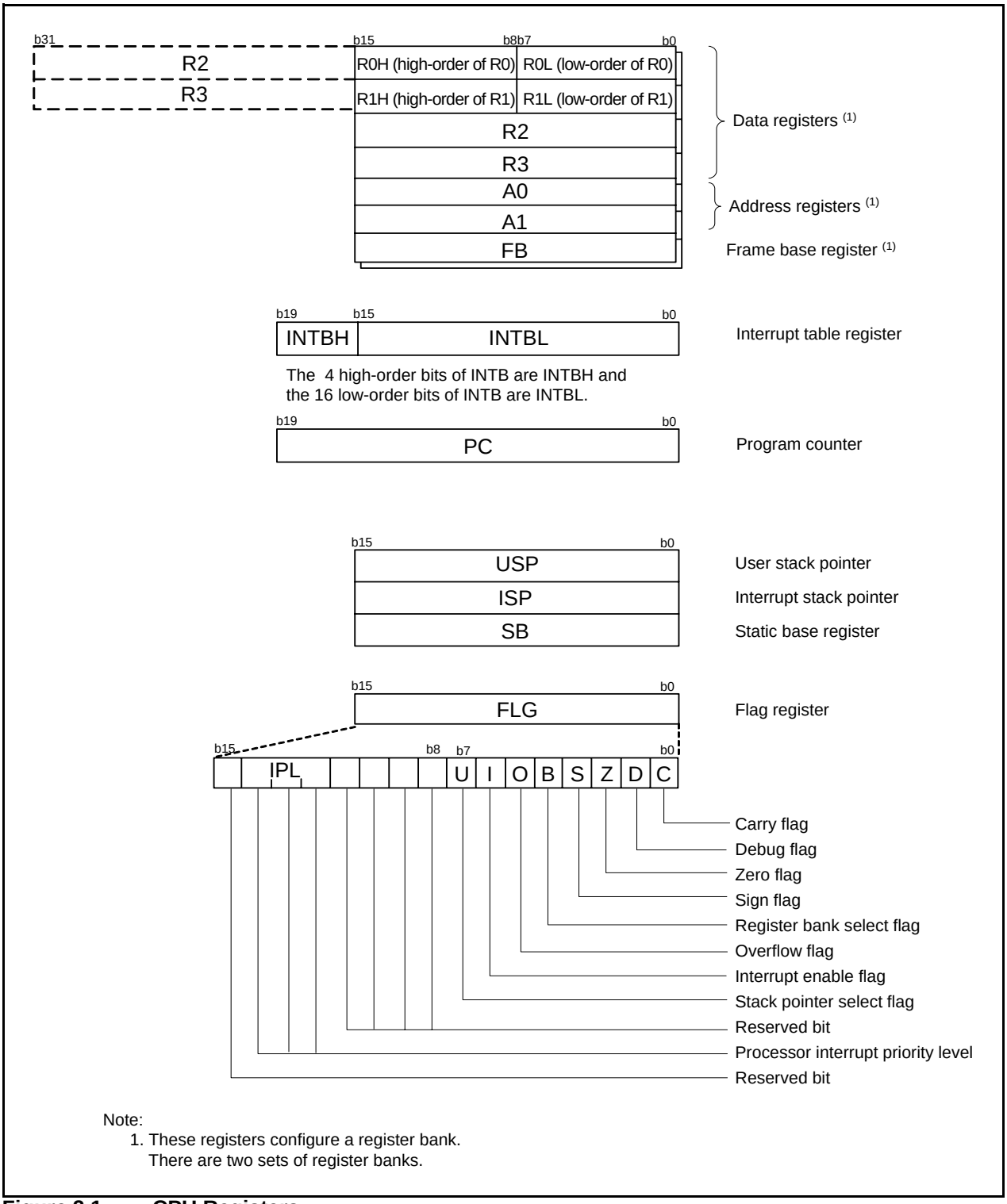
I: Input O: Output I/O: Input and output

Note:

1. Contact the oscillator manufacturer for oscillation characteristics.

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register banks.



Note:
1. These registers configure a register bank.
There are two sets of register banks.

Figure 2.1 CPU Registers

5. Electrical Characteristics

5.1 Absolute Maximum Ratings

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter		Condition	Rated Value	Unit
V_{CC}/AV_{CC}	Supply voltage			–0.3 to 6.5	V
V_I	Input voltage	XIN	XIN-XOUT oscillation on (oscillation buffer ON) (1)	–0.3 to 1.65	V
		XIN	XIN-XOUT oscillation on (oscillation buffer OFF) (1)	–0.3 to V_{CC} + 0.3	V
		VL1		–0.3 to VL2	V
		VL2	R8C/L35C	VL1 to VL4	V
			R8C/L36C, R8C/L38C, R8C/L3AC	VL1 to VL3	V
		VL3		VL2 to VL4	V
		VL4		VL3 to 6.5	V
		Other pins		–0.3 to V_{CC} + 0.3	V
V_O	Output voltage	XOUT	XIN-XOUT oscillation on (oscillation buffer ON) (1)	–0.3 to 1.65	V
		XOUT	XIN-XOUT oscillation on (oscillation buffer OFF) (1)	–0.3 to V_{CC} + 0.3	V
		VL1		–0.3 to VL2 (2)	V
		VL2	R8C/L35C	VL1 to VL4	V
			R8C/L36C, R8C/L38C, R8C/L3AC	VL1 to VL3	V
		VL3		VL2 to VL4	V
		VL4		–0.3 to 6.5	V
		CL1, CL2		–0.3 to 6.5	V
		COM0 to COM7		–0.3 to VL4	V
		SEG0 to SEG55		–0.3 to VL4	V
		Other pins		–0.3 to V_{CC} + 0.3	V
P_d	Power dissipation		–40°C ≤ T_{opr} ≤ 85°C	500	mW
T_{opr}	Operating ambient temperature			–20 to 85 (N version) / –40 to 85 (D version)	°C
T_{stg}	Storage temperature			–65 to 150	°C

Notes:
1. For the register settings for each operation, refer to **7. I/O Ports** and **9. Clock Generation Circuit** in the User's Manual: Hardware.
2. The VL1 voltage should be VCC or below.

5.2 Recommended Operating Conditions

Table 5.2 Recommended Operating Conditions
(Vcc = 1.8 to 5.5 V and Topr = −20 to 85°C (N version) / −40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter				Conditions	Standard			Unit
						Min.	Typ.	Max.	
Vcc/AVcc	Supply voltage					1.8	—	5.5	V
Vss/AVss	Supply voltage					—	0	—	V
VIH	Input “H” voltage	Other than CMOS input			4.0 V ≤ Vcc ≤ 5.5 V	0.8 Vcc	—	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.8 Vcc	—	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.9 Vcc	—	Vcc	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0.5 Vcc	—	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.55 Vcc	—	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.65 Vcc	—	Vcc	V
				Input level selection : 0.5 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0.65 Vcc	—	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.7 Vcc	—	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.8 Vcc	—	Vcc	V
				Input level selection : 0.7 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0.85 Vcc	—	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.85 Vcc	—	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.85 Vcc	—	Vcc	V
VIL	Input “L” voltage	Other than CMOS input			4.0 V ≤ Vcc ≤ 5.5 V	0	—	0.2 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	—	0.2 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	—	0.05 Vcc	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0	—	0.2 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	—	0.2 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	—	0.2 Vcc	V
				Input level selection : 0.5 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0	—	0.4 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	—	0.3 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	—	0.2 Vcc	V
				Input level selection : 0.7 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0	—	0.55 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	—	0.45 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	—	0.35 Vcc	V
IOH(sum)	Peak sum output “H” current	Sum of all pins IOH(peak)				—	—	−160	mA
IOH(sum)	Average sum output “H” current	Sum of all pins IOH(avg)				—	—	−80	mA
IOH(peak)	Peak output “H” current	Port P10, P11 (2)				—	—	−40	mA
		Other pins				—	—	−10	mA
IOH(avg)	Average output “H” current (1)	Port P10, P11 (2)				—	—	−20	mA
		Other pins				—	—	−5	mA
IOL(sum)	Peak sum output “L” current	Sum of all pins IOL(peak)				—	—	160	mA
IOL(sum)	Average sum output “L” current	Sum of all pins IOL(avg)				—	—	80	mA
IOL(peak)	Peak output “L” current	Port P10, P11 (2)				—	—	40	mA
		Other pins				—	—	10	mA
IOL(avg)	Average output “L” current (1)	Port P10, P11 (2)				—	—	20	mA
		Other pins				—	—	5	mA
f(XIN)	XIN clock input oscillation frequency				2.7 V ≤ Vcc ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ Vcc < 2.7 V	—	—	5	MHz
f(XCIN)	XCIN clock input oscillation frequency				1.8 V ≤ Vcc ≤ 5.5 V	—	32.768	50	kHz
fOCO40M	When used as the count source for timer RC, timer RD, or timer RG (3)				2.7 V ≤ Vcc ≤ 5.5 V	32	—	40	MHz
fOCO-F	fOCO-F frequency				2.7 V ≤ Vcc ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ Vcc < 2.7 V	—	—	5	MHz
—	System clock frequency				2.7 V ≤ Vcc ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ Vcc < 2.7 V	—	—	5	MHz
f(BCLK)	CPU clock frequency				2.7 V ≤ Vcc ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ Vcc < 2.7 V	—	—	5	MHz

Notes:
1. The average output current indicates the average value of current measured during 100 ms.
2. This applies when the drive capacity of the output transistor is set to High by registers P10DRR and P11DRR. When the drive capacity is set to Low, the value of any other pin applies.
3. fOCO40M can be used as the count source for timer RC, timer RD, or timer RG in the range of Vcc = 2.7 V to 5.5V.

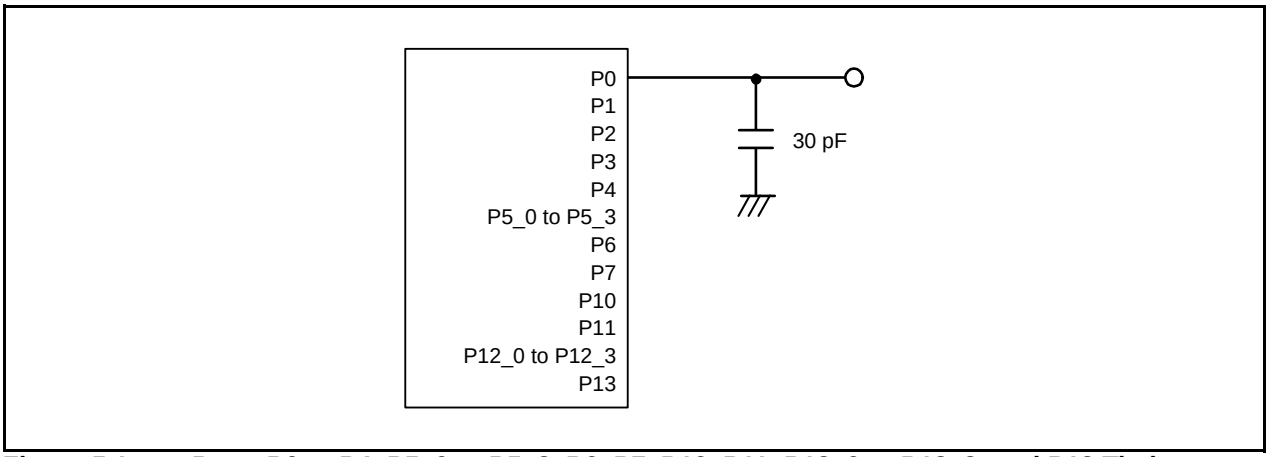


Figure 5.1 Ports P0 to P4, P5_0 to P5_3, P6, P7, P10, P11, P12_0 to P12_3, and P13 Timing Measurement Circuit

5.4 DC Characteristics

Table 5.17 DC Characteristics (1) [4.0 V ≤ Vcc ≤ 5.5 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output “H” voltage	Port P10, P11 (1)	V_{CC} = 5V	I_{OH} = –20 mA	V_{CC} – 2.0	—	V_{CC}	V
		Other pins	V_{CC} = 5V	I_{OH} = –5 mA	V_{CC} – 2.0	—	V_{CC}	V
		XOUT	V_{CC} = 5V	I_{OH} = –200 μA	1.0	—	—	V
V_{OL}	Output “L” voltage	Port P10, P11 (1)	V_{CC} = 5V	I_{OL} = 20 mA	—	—	2.0	V
		Other pins	V_{CC} = 5V	I_{OL} = 5 mA	—	—	2.0	V
		XOUT	V_{CC} = 5V	I_{OL} = 200 μA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{INT4}$, $\overline{INT5}$, $\overline{INT6}$, $\overline{INT7}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, KI4, KI5, KI6, KI7, TRAIO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, TRGCLKA, TRGCLKB, TRGIOA, TRGIOB, $\overline{ADTRG}$, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.05	0.5	—	V
		$\overline{RESET}$, $\overline{WKUP0}$			0.1	1.0	—	V
I_{IH}	Input “H” current		VI = 5.0 V, V_{CC} = 5.0 V		—	—	5.0	μA
I_{IL}	Input “L” current		VI = 0 V, V_{CC} = 5.0 V		—	—	–5.0	μA
R_{PULLUP}	Pull-up resistance		VI = 0 V, V_{CC} = 5.0 V		25	50	100	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	14	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Note:
1. This applies when the drive capacity of the output transistor is set to High by registers P10DRR and P11DRR. When the drive capacity is set to Low, the value of any other pin applies.

Table 5.20 DC Characteristics (4) [2.7 V ≤ Vcc < 4.0 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition								Standard			Unit
			Oscillation Circuit		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ. (3)	Max.	
			XIN (2)	XCIN	High-Speed (fOCO-F)	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	—		—	7.0	14.5	mA
			10 MHz	Off	Off	125 kHz	No division	—		—	3.6	10	mA
			20 MHz	Off	Off	125 kHz	Divide-by-8	—		—	3.0	—	mA
			10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	—	mA
		High-speed on-chip oscillator mode	Off	Off	20 MHz	125 kHz	No division	—		—	7.0	14.5	mA
			Off	Off	20 MHz	125 kHz	Divide-by-8	—		—	3.0	—	mA
			Off	Off	10 MHz	125 kHz	No division	—		—	4.0	—	mA
			Off	Off	10 MHz	125 kHz	Divide-by-8	—		—	1.7	—	mA
			Off	Off	4 MHz	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRD = 1 MSTTRC = 1 MSTTRG = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 VCA20 = 0		—	85	390	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 VCA20 = 0		—	90	400	µA
			Off	32 kHz	Off	Off	No division	FMSTP = 1 VCA20 = 0	Flash memory off Program operation on RAM	—	50	—	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off	—	5	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 0	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode	LCD drive control circuit (4) When external division resistors are used	—	5	—	µA
										LCD drive control circuit (5) When the internal voltage multiplier is used	—	11	—	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode		—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off		—	2	5.0	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off		—	13.0	—	µA
		Power-off mode	Off	Off	Off	Off	—	—	Topr = 25°C		—	0.02	0.2	µA
			Off	Off	Off	Off	—	—	Topr = 85°C		—	0.3	—	µA

Notes:
1. Vcc = 2.7 V to 4.0 V, single chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. Vcc = 3.0 V
4. VLCD = Vcc, external division resistors are used for VL4 to VL1, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open. The standard value does not include the current that flows through external division resistors.
5. The internal voltage multiplier is used, bits LVLS3 to LVLS0 in the LCR1 register = 1011b, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open.

Table 5.21 DC Characteristics (5) [1.8 V ≤ Vcc < 2.7 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V_{OH}	Output “H” voltage	Port P10, P11 (1)	I_{OH} = –2 mA	V_{CC} – 0.5	—	V_{CC}	V
		Other pins	I_{OH} = –1 mA	V_{CC} – 0.5	—	V_{CC}	V
		XOUT	I_{OH} = –200 μA	1.0	—	—	V
V_{OL}	Output “L” voltage	Port P10, P11 (1)	I_{OL} = 2 mA	—	—	0.5	V
		Other pins	I_{OL} = 1 mA	—	—	0.5	V
		XOUT	I_{OL} = 200 μA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{INT4}$, INT5, $\overline{INT6}$, INT7, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, $\overline{KI4}$, $\overline{KI5}$, $\overline{KI6}$, $\overline{KI7}$, TRAIO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, TRGCLKA, TRGCLKB, $\overline{TRGIOA}$, TRGIOB, $\overline{ADTRG}$, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO		0.05	0.4	—	V
		$\overline{RESET}$, $\overline{WKUP0}$		0.1	0.8	—	V
I_{IH}	Input “H” current		VI = 1.8 V, V_{CC} = 1.8 V	—	—	4.0	μA
I_{IL}	Input “L” current		VI = 0 V, V_{CC} = 1.8 V	—	—	–4.0	μA
R_{PULLUP}	Pull-up resistance		VI = 0 V, V_{CC} = 1.8 V	60	160	420	kΩ
R_{fXIN}	Feedback resistance	XIN		—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN		—	14	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode	1.8	—	—	V

Note:
1. This applies when the drive capacity of the output transistor is set to High by registers P10DRR and P11DRR. When the drive capacity is set to Low, the value of any other pin applies.

5.5 AC Characteristics

Table 5.23 Timing Requirements of Synchronous Serial Communication Unit (SSU) (V_{CC} = 1.8 to 5.5 V, V_{SS} = 0 V, and T_{opr} = −20 to 85°C (N version) / −40 to 85°C (D version), unless otherwise specified.)

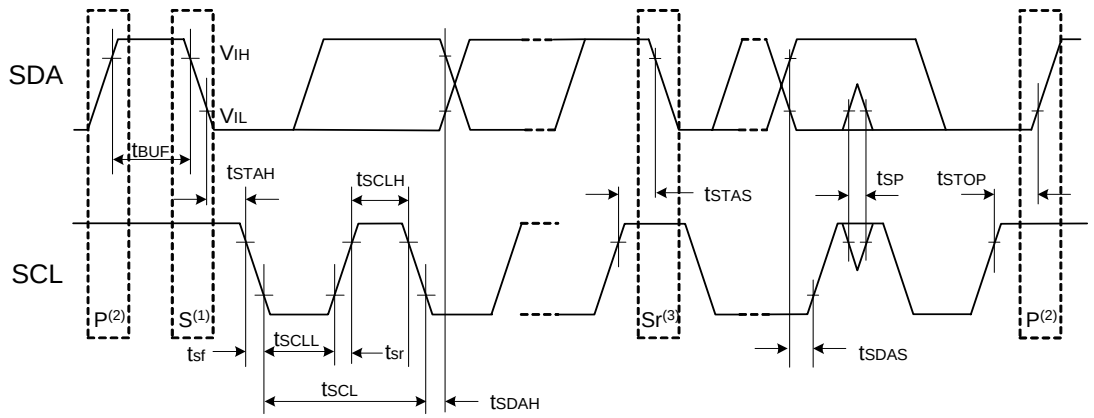
Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
t_{SUCYC}	SSCK clock cycle time			4	—	—	t_{CYC} (1)
t_{HI}	SSCK clock “H” width			0.4	—	0.6	t_{SUCYC}
t_{LO}	SSCK clock “L” width			0.4	—	0.6	t_{SUCYC}
t_{RISE}	SSCK clock rising time	Master		—	—	1	t_{CYC} (1)
		Slave		—	—	1	µs
t_{FALL}	SSCK clock falling time	Master		—	—	1	t_{CYC} (1)
		Slave		—	—	1	µs
t_{SU}	SSO, SSI data input setup time			100	—	—	ns
t_H	SSO, SSI data input hold time			1	—	—	t_{CYC} (1)
t_{LEAD}	$\overline{SCS}$ setup time	Slave		1t_{CYC} + 50	—	—	ns
t_{LAG}	$\overline{SCS}$ hold time	Slave		1t_{CYC} + 50	—	—	ns
t_{OD}	SSO, SSI data output delay time			—	—	1	t_{CYC} (1)
t_{SA}	SSI slave access time		2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	1.5t_{CYC} + 100	ns
			1.8 V ≤ V_{CC} < 2.7 V	—	—	1.5t_{CYC} + 200	ns
t_{OR}	SSI slave out open time		2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	1.5t_{CYC} + 100	ns
			1.8 V ≤ V_{CC} < 2.7 V	—	—	1.5t_{CYC} + 200	ns

Note:
1. 1t_{CYC} = 1/f1(s)

Table 5.24 Timing Requirements of I²C bus Interface (1)
(Vcc = 1.8 to 5.5 V, Vss = 0 V, and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
tSCL	SCL input cycle time		12tCYC + 600 (1)	—	—	ns
tSCLH	SCL input “H” width		3tCYC + 300 (1)	—	—	ns
tSCLL	SCL input “L” width		5tCYC + 500 (1)	—	—	ns
tsf	SCL, SDA input fall time		—	—	300	ns
tSP	SCL, SDA input spike pulse rejection time		—	—	1tCYC (1)	ns
tBUF	SDA input bus-free time		5tCYC (1)	—	—	ns
tSTAH	Start condition input hold time		3tCYC (1)	—	—	ns
tSTAS	Retransmit start condition input setup time		3tCYC (1)	—	—	ns
tSTOP	Stop condition input setup time		3tCYC (1)	—	—	ns
tSDAS	Data input setup time		1tCYC + 40 (1)	—	—	ns
tSDAH	Data input hold time		10	—	—	ns

Note:
1. 1tCYC = 1/f1(s)



Notes:
1. Start condition
2. Stop condition
3. Retransmit start condition

Figure 5.7 I/O Timing of I²C bus Interface

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.

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